

300493

2023-001

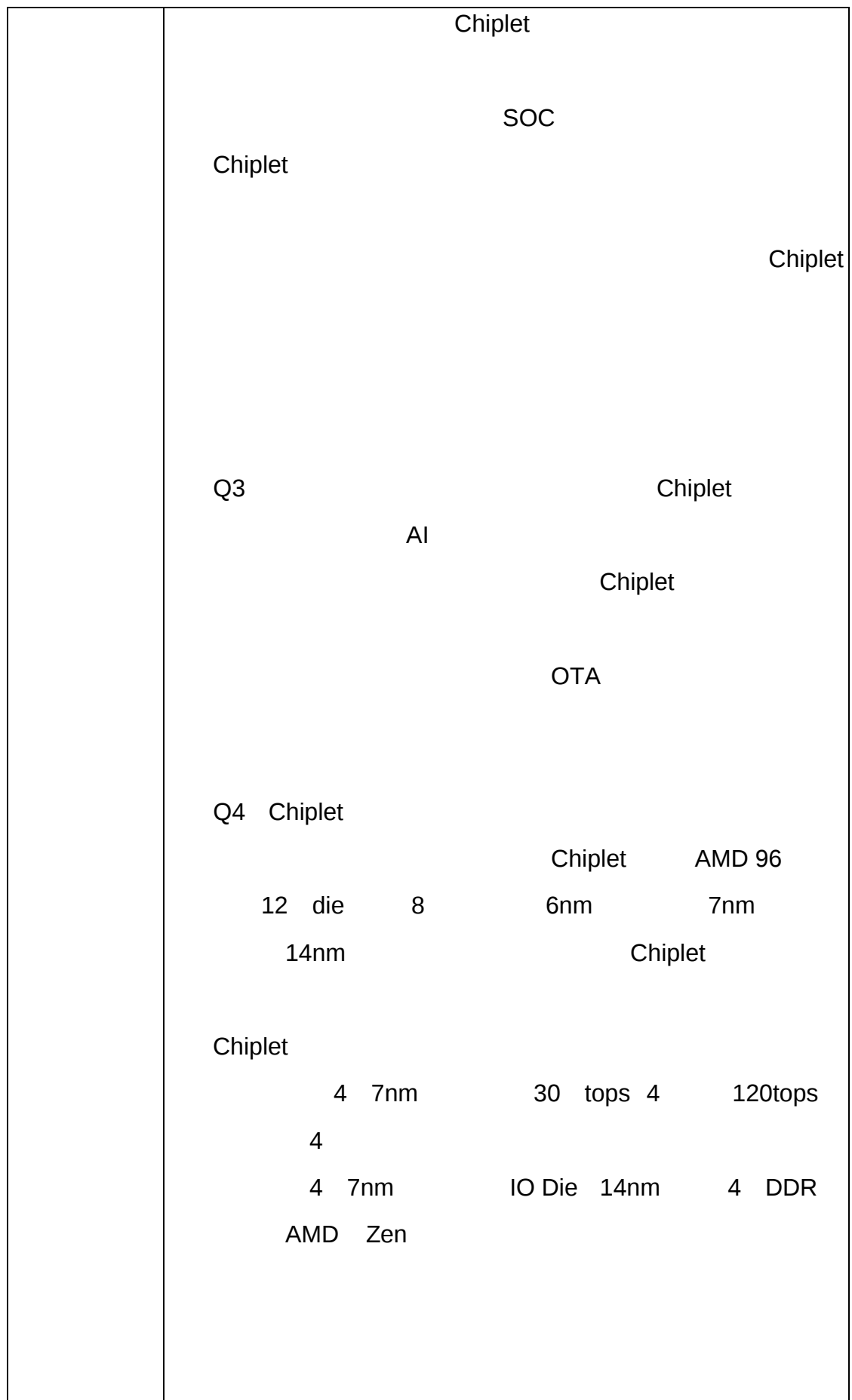
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	2023 2 8 14:00-16:00			
	727 6 2			
	Chiplet			
	SOC			

AIGC

AIOT

MEMS



	IC
	Q10 Chiplet PMUT
	Q11 ? KDG KNOWN GOOD DIE KGD wafer die KNOWN GOOD DIE IC AR VR CGM
	Chiplet
	Q12 Chiplet IP KGD wifi wifi AI WIFI7+AI IP Chippet
	Q13 active silicon interposer Base Die passive silicon interposer IO active interposer

	Q14 150600AIOT 150 600 Q15 IP Q16Chiplet 1nmC4 bump die to waferwafer on wafer Q17Chiplet
	2023 2 8